

<Intelligent Power Modules>

PM450RG1C065

FLAT-BASE TYPE INSULATED PACKAGE

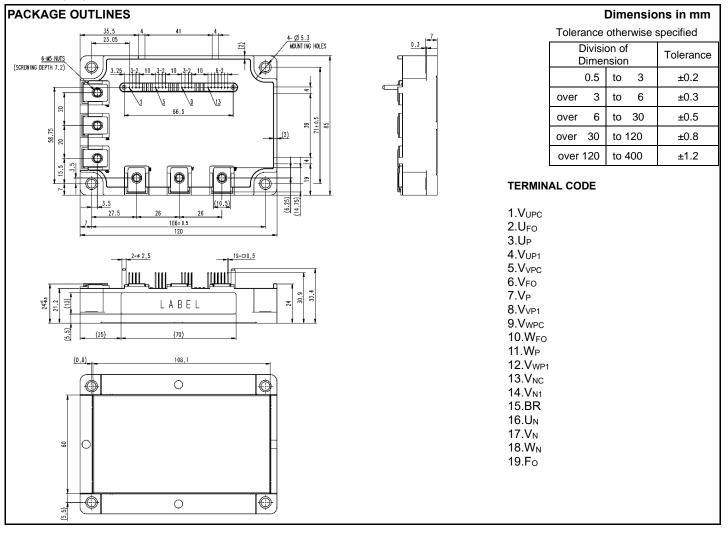
FEATURE

- a) Adopting Full-Gate CSTBT[™] chip.
- b) The over-temperature protection which detects the chip surface temperature of CSTBT[™] is adopted.
- c) Error output signal is available from each protection upper and lower arm of IPM.
- d) Outputting an error signal corresponding to the abnormal state (error mode identification)

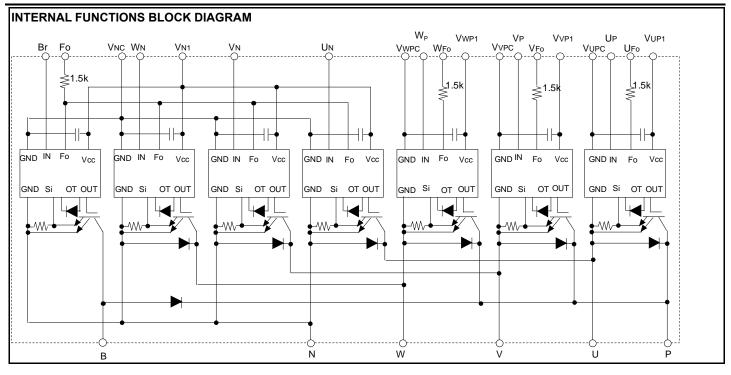
UL Recognized under UL1557, File No. E323585 This product is compliant with the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive 2011/65/EU and (EU)2015/863.

APPLICATION

General purpose inverter, servo drives and other motor controls



<Intelligent Power Modules> PM450RG1C065 HIGH POWER SWITCHING USE INSULATED TYPE



MAXIMUM RATINGS (Tvj = 25°C, unless otherwise noted)

INVERTER PART

Symbol	Parameter	Conditions	Ratings	Unit
V _{CES}	Collector-Emitter Voltage	V _D =15 V, V _{CIN} =15 V	650	V
I _C	Callester Coment	T _c =25 °C	450	
I _{CRM}	Collector Current	Pulse	675	A
P _{tot}	Total Power Dissipation	T _c =25 °C	1388	W
l _E	Emitter Current	T _c =25 °C	450	
I _{ERM}	(Free-wheeling Diode Forward current)	Pulse	675	A
Τvj	Junction Temperature	(Note5)	-20 ~ +150	°C

*: Tc measurement point is just under the chip.

BRAKE PART

Symbol	Parameter	Conditions	Ratings	Unit
V _{CES}	Collector-Emitter Voltage	V _D =15 V, V _{CIN} =15 V	650	V
lc		T _c =25 °C	200	
I _{CRM}	Collector Current	Pulse	300	A
P _{tot}	Total Power Dissipation	T _c =25 °C	735	W
V _{R(DC)}	Diode Rated Reverse DC Voltage	T _c =25 °C	650	V
l _F	Diode Forward Current	T _c =25 °C	200	Α
Tvj	Junction Temperature	(Note5)	-20 ~ +150	°C

*: Tc measurement point is just under the chip.

CONTROL PART

Symbol	Parameter	Conditions	Ratings	Unit
VD	Supply Voltage	Applied between: V_{UP1} - V_{UPC} , V_{VP1} - V_{VPC} , V_{WP1} - V_{WPC} , V_{N1} - V_{NC}	20	V
V _{CIN}	Input Voltage	Applied between: U _P -V _{UPC} , V _P -V _{VPC} , W _P -V _{WPC} , U _N , V _N , W _N , Br -V _{NC}	20	V
V _{FO}	Fault Output Supply Voltage	Applied between: U_{FO} - V_{UPC} , V_{FO} - V_{VPC} , W_{FO} - V_{WPC} , FO- V_{NC}	20	V
I _{FO}	Fault Output Current	Sink current at U_{FO} , V_{FO} , W_{FO} , Fo terminals	20	mA

TOTAL SYSTEM

TOTAL				
Symbol	Parameter	Conditions	Ratings	Unit
V _{CC(PROT)}	Supply Voltage Protected by SC	V _D =13.5 V∼16.5 V, Inverter Part, Tvj=+125°C start	400	V
T _{stg}	Storage Temperature	-	-40 ~ +125	°C
Tc	Operating Case Temperature	(Note5)	-20 ~ +125	°C
V _{isol}	Isolation Voltage	60Hz, Sinusoidal, Charged part to Base plate, AC 1min, RMS	2500	V

*: Tc measurement point is just under the chip.

THERMAL RESISTANCE

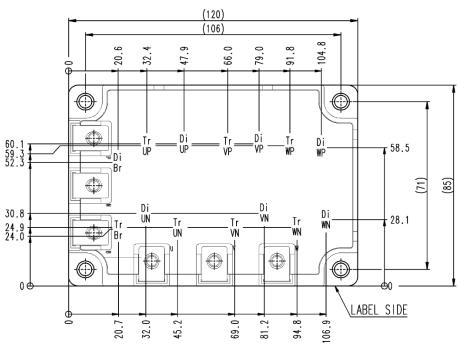
Symbol	Parameter	Conditions		Unit		
Symbol	Falameter	Conditions	Min.	Тур.	Max.	Unit
R _{th(j-c)Q}	Thermal Resistance	Inverter, Junction to case, IGBT, per 1 element (Note1)	-	-	0.09	
R _{th(j-c)D}		Inverter, Junction to case, FWD, per 1 element (Note1)	-	-	0.14	K/W
$R_{th(j-c)Q}$		Brake, Junction to case, IGBT, per 1 element (Note1)	-	-	0.17	r\/ vv
$R_{th(j-c)D}$		Brake, Junction to case, FWD, per 1 element (Note1)	-	-	0.27	
$R_{th(c-s)}$	Contact Thermal Resistance	Case to heat sink, per 1 module, Thermal grease applied (Note.1, 2, 5)	-	8.4	-	K/kW

Note1. If you use this value, $R_{th(s-a)}$ should be measured just under the chips.

Note2. Typical value is by thermally conductive grease of λ =0.9W/(m·K), D_(C-S)=50 µm.

CHIP LOCATION (Top view)

Dimension in mm, torelance: ±1mm



Tr** Di**	: IGBT : FWD	
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ELECTRICAL CHARACTERISTICS (Tvj= 25°C, unless otherwise noted)

INVERTER PART

Quanta al	Denementen				Limits			1.1
Symbol	Parameter	Conditions			Min.	Тур.	Max.	Unit
			T	Terminal	-	-	2.1	
N/	Collector Emitter Seturation Valtage	V _D =15 V, I _C =450 A	Tvj=25 °C	Chip	-	1.25	-	v
V _{CEsat}	Collector-Emitter Saturation Voltage		Tui-405 %0	Terminal	-	-	2.35	v
		V _{CIN} =0 V, Pulsed, (Fig.1)	Tvj=125 °C	Chip	-	1.33	-	
		V _D =15 V, I _E =450A, Tvj=25 °C		Terminal	-	-	2.2	
\/	Emitter Cellecter Veltere		Chip	-	1.40	-	v	
V _{EC}	Emitter-Collector Voltage	V _{CIN} = 15 V, pulsed, (Fig.2) Tvj=125 °C	Tui-125 °C	Terminal	-	-	2.3	v
			Chip	-	1.45	-		
t _{on}		V_D =15 V, V_{CIN} =0 V \leftrightarrow 15 V, V_{CC} =300 V, I _C =450A, Tvj=125 °C, Inductive Load		0.3	0.6	1.2		
t _{rr}					-	0.2	0.65	
t _{c(on)}	Switching Time				-	0.2	0.75	μs
t _{off}	1			-	1.3	2.3		
t _{c(off)}		(Fig.3, 4)			-	0.2	0.4	
		$V_{CE}=V_{CES}, V_{D}=15 V,$		Tvj=25 °C	-	-	1	
I _{CES}	Collector-Emitter Cut-off Current	V _{CIN} =15 V (Fig.5)		Tvj=125 °C	-	-	10	mA

BRAKE PART

Symbol	Deremeter	Conditions			Limits			1.1
Symbol	Parameter	Condition	S		Min.	Тур.	Max.	Unit
		V _D =15 V, I _C =200A	Tvj=25 °C	Terminal	-	-	2.0	
V		VD-13 V, IC-200A	10]-23 C	Chip	-	1.25	-	V
V _{CEsat}	Collector-Emitter Saturation Voltage	V _{CIN} =0 V, Pulsed, (Fig.1)	Tvj=125 °C	Terminal	-	-	2.25	
				Chip	-	1.33	-	
			Tvj=25 °C	Terminal	-	-	2.1	
V	Diada Farward Valtara			Chip	-	1.40	-	v
V _{FM}	Diode Forward Voltage	I _F =200A	Tvj=125 °C	Terminal	-	-	2.2	v
		1 1		Chip	-	1.45	-	
1	Collector-Emitter Cut-off Current	$V_{CE} = V_{CES}, V_{D} = 15 V, V_{CIN} = 15 V$ (Fig.5)		Tvj=25 °C	-	-	1	m (
I _{CES}				Tvj=125 °C	-	-	10	mA

ELECTRICAL CHARACTERISTICS (Tvj = 25°C, unless otherwise noted)

CONTROL PART

C: make al	Devenueter	Conditions	Conditions		Limits			
Symbol	Parameter	Conditions			Тур.	Max.	Unit	
			V _{P1} -V _{PC}	-	4	6		
1		V_{D} =15 V, V_{CIN} =15 V	V _{N1} -V _{NC}	-	16	24]	
ID	Circuit Current	V_D =15 V, V_{CIN} =0 V \leftrightarrow 15 V, V_{CC} =400 V	V _{P1} -V _{PC}	-	52	63	mA	
		l _c =0A, Tvj=125 °C, f _c ≤20kHz	V _{N1} -V _{NC}	-	183	220	1	
$V_{th(ON)}$	Input ON Threshold Voltage	Applied between:		1.2	1.5	1.8		
$V_{th(OFF)}$	Input OFF Threshold Voltage	$U_{P}\text{-}V_{UPC}, V_{P}\text{-}V_{VPC}, W_{P}\text{-}V_{WPC}, U_{N}, V_{N}, W_{N},$	Br-V _{NC}	1.7	2.0	2.3	V	
			Inverter	675	-	-		
SC Short Circ	Short Circuit Trip Level	-20≤Tvj≤125 °C, V _D =15 V (Fig.3, 6)	Brake	300	-	-	A	
t _{d(SC)}	Short Circuit Current Delay Time	V _D =15 V, Tvj=125 °C (Fig.3, 6)		-	2.0	-	μs	
ОТ			Trip level	150	-	-	*0	
OT _(hys)	Over Temperature Protection	Detect temperature of IGBT chip surface	Hysteresis	-	20	-	- °C	
UVt	Supply Circuit		Trip level	11.0	12.0	12.7		
UVr	Under-Voltage Protection	-	Reset level	-	12.5	-	V	
I _{FO(H)}	Fourth Outrout Outroant			-	-	0.01		
I _{FO(L)}	Fault Output Current	V _D =15 V, V _{FO} =15 V (Note3)		-	10	15	mA	
			OT	-	8.0	-	ms	
t _{FO}	Fault Output Pulse Width	V _D =15 V (Note3)	UV	-	4.0	-		
			SC	-	2.0	-		

Note3. Fault output is given only when the internal SC, OT & UV protections schemes of either upper or lower arm device operate to protect it.

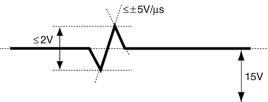
MECHANICAL RATINGS AND CHARACTERISTICS

Symbol	Parameter	Conditions		Limits		
				Тур.	Max.	Unit
Ms	Mounting Torque	Mounting part screw : M5	2.5	3.0	3.5	N•m
Mt	Mounting Torque	Main terminal part screw : M5	2.5	3.0	3.5	IN•III
m	mass	-	-	425	-	g

RECOMMENDED CONDITIONS FOR USE

Symbol	Parameter	Conditions	Recommended value	Unit
V _{cc}	Supply Voltage	Applied across P-N terminals	≤ 400	V
V _D	Control Supply Voltage	Applied between : V _{UP1} -V _{UPC} , V _{VP1} -V _{VPC} , V _{WP1} -V _{WPC} ,V _{N1} -V _{NC} (Note4)	15.0±1.5	V
V _{CIN(ON)}	Input ON Voltage	Applied between :	≤ 0.8	V
V _{CIN(OFF)}	Input OFF Voltage	$U_{P}\text{-}V_{UPC}, V_{P}\text{-}V_{VPC}, W_{P}\text{-}V_{WPC}, U_{N}, V_{N}, W_{N}, Br\text{-}V_{NC}$	≥ 9.0	v
f _{PWM}	PWM Input Frequency	Using Application Circuit of Fig. 8	≤ 20	kHz
t _{dead}	Arm Shoot-through Blocking Time	For IPM's each input signals (Fig.7)	≥ 2.0	μs

Note4. With ripple satisfying the following conditions: dv/dt swing ≤ ±5 V/µs, Variation ≤ 2 V peak to peak



GND

Note5. Long term performance related to thermal conductive material such as thermal grease (including but not limited to aspects such as the increase of thermal resistance due to pumping out, etc.) should be verified under your specific application conditions. Each temperature condition (Tvj, Tc) must be maintained below the maximum rated temperature throughout consideration of the temperature rise even for long term usage.

PRECAUTIONS FOR TESTING

VD(a

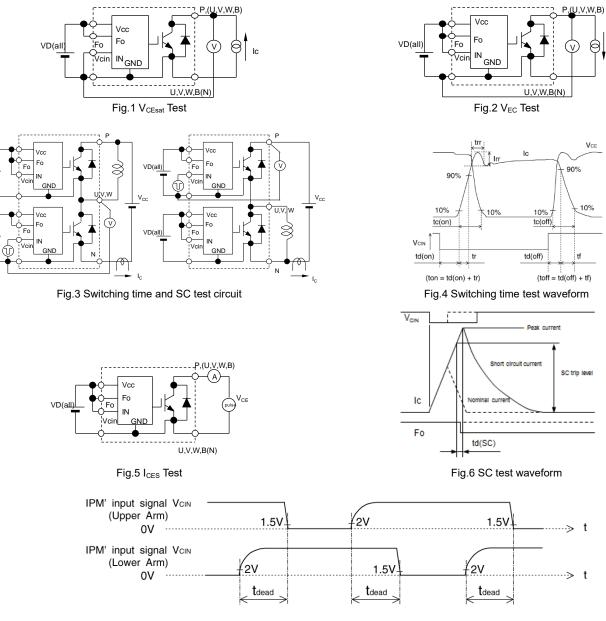
VD(all

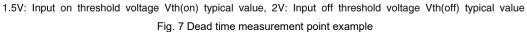
1. Before applying any control supply voltage (V_D), the input terminals should be pulled up by resistors, etc. to their corresponding supply voltage and each input signal should be kept off state.

After this, the specified ON and OFF level setting for each input signal should be done.

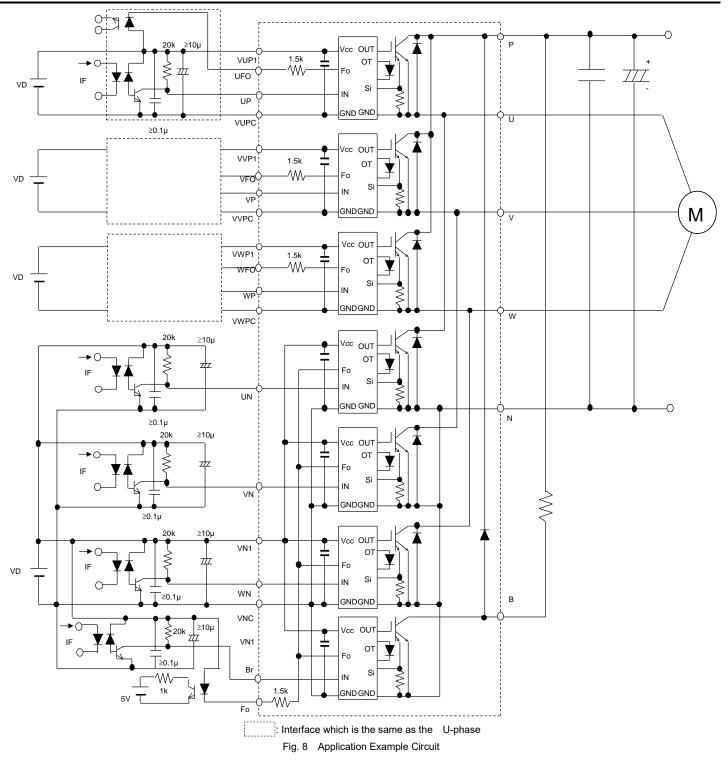
2. When performing "SC" tests, the turn-off surge voltage spike at the corresponding protection operation should not be allowed to rise above V_{CES} rating of the device.

(These test should not be done by using a curve tracer or its equivalent.)



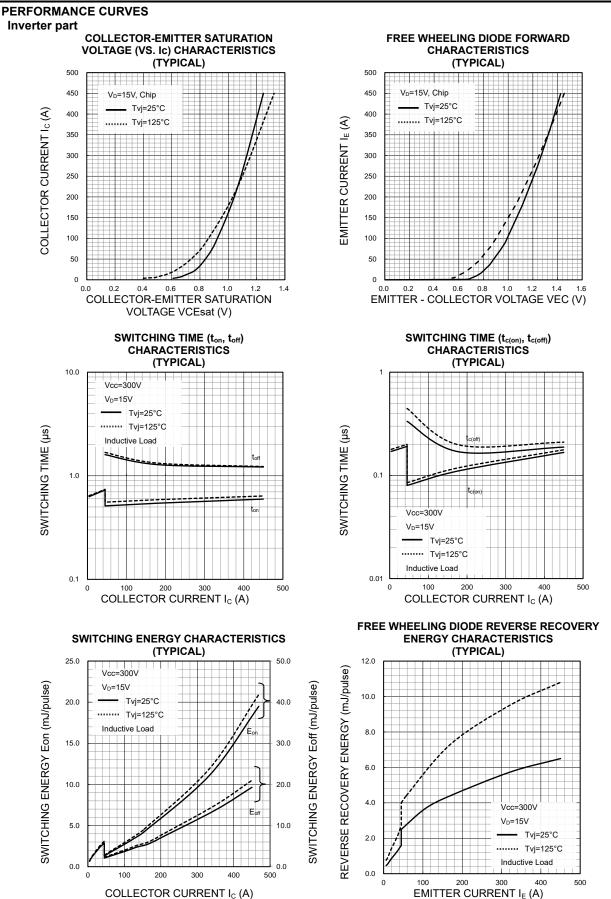


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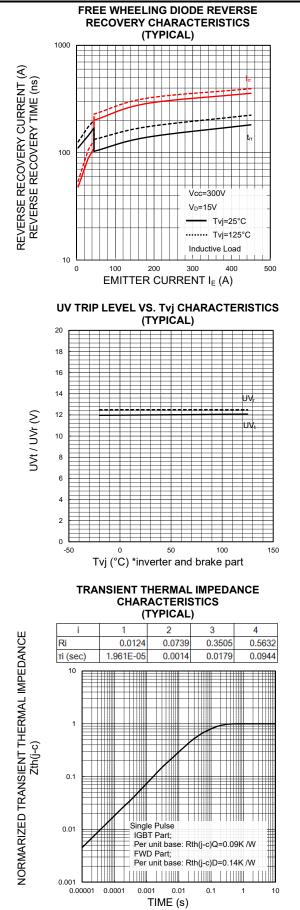


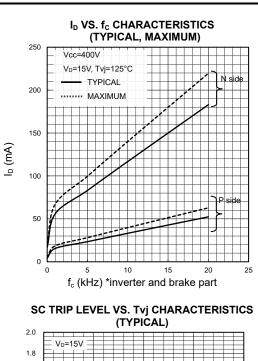
NOTES FOR STABLE AND SAFE OPERATION ;

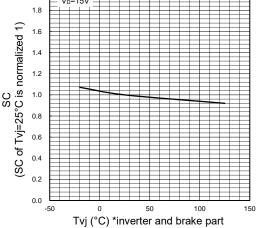
- Design the PCB pattern to minimize wiring length between opto-coupler and IPM's input terminal, and also to minimize the stray capacity between the input and output wirings of opto-coupler.
- Connect low impedance capacitor between the Vcc and GND terminal of each fast switching opto-coupler.
- Fast switching opto-couplers: t_{PLH} , $t_{PHL} \le 0.8 \mu s$, Use High CMR type.
- Slow switching opto-coupler: CTR > 100% (*can be applied to Brake part input signal, in this case, resistor should be selected properly).
- Use 4 isolated control power supplies (V_D). Also, care should be taken to minimize the instantaneous voltage charge of the power supply.
- Make inductance of DC bus line as small as possible, and minimize surge voltage using snubber capacitor between P and N terminal.

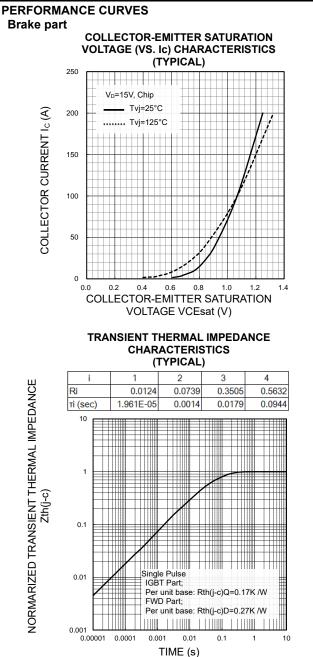


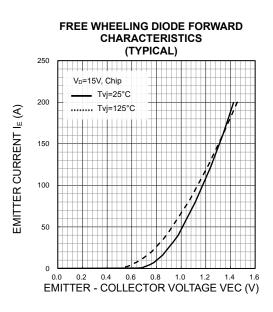
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Note: The characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

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